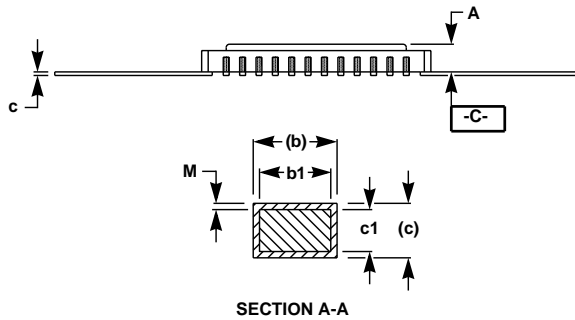
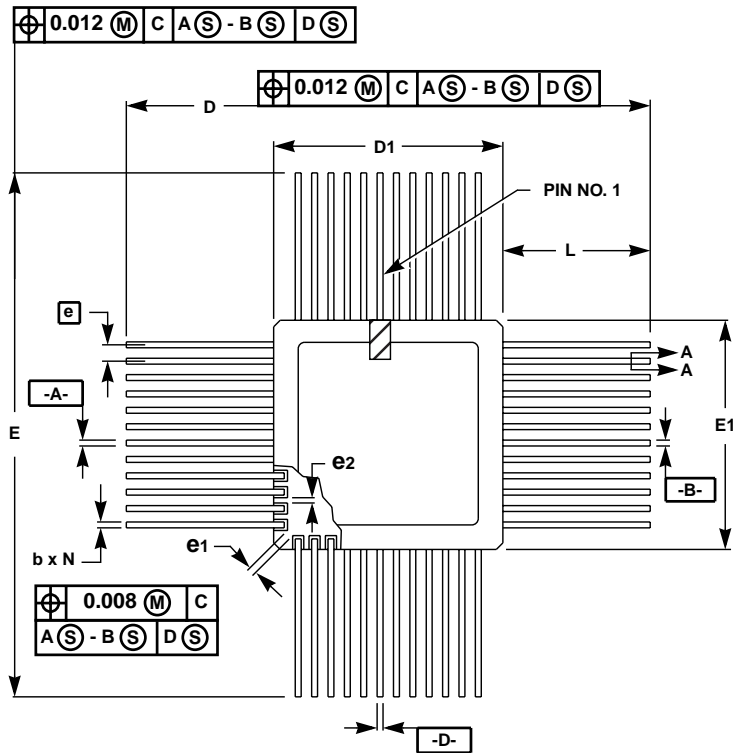


Ceramic Quad Flatpack (CQFP)



R48.A

48 LEAD CERAMIC QUAD FLATPACK PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.065	0.135	1.65	3.43	-
b	0.008	0.015	0.20	0.38	2
b1	0.008	0.012	0.20	0.31	2
c	0.009	0.016	0.23	0.41	2
c1	0.009	0.013	0.23	0.33	2
D	1.055	1.275	26.80	32.39	-
E	1.055	1.275	26.80	32.39	-
D1	0.555	0.575	14.10	14.61	-
E1	0.555	0.575	14.10	14.61	4
e	0.040 BSC		1.02 BSC		-
e1	0.015	-	0.38	-	-
e2	0.007	-	0.18	-	-
L	0.250	0.350	6.35	8.89	-
Q	NA	NA	NA	NA	-
M	-	0.0015	-	0.04	2
N	48		48		3

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NOTES:

1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. N is the maximum number of terminal positions.
4. Measure dimension e1 at all four corners.
5. For bottom-brazed lead packages, no organic or polymeric materials shall be molded to the bottom of the package to cover the leads.
6. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
7. Controlling dimension: Inch.